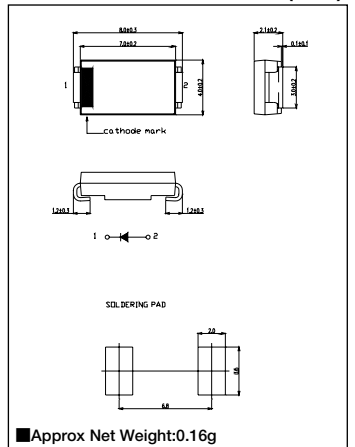


3A Avg. 100 Volts Standard Recovery Diode NSD03A10

■最大定格 Maximum Ratings

Item	Symbol	Conditions	Unit
くり返しピーク逆電圧 Repetitive Peak Reverse Voltage	V_{RRM}	100	V
平均整流電流 Average Rectified Output Current	I_O	50Hz 正弦半波抵抗負荷 50Hz half sine wave Resistance load	$T_a=25^{\circ}C^{*1}$ 1.57 $T_l=108^{\circ}C^{*2}$ 3.0 A
実効順電流 R.M.S. Forward Current	$I_{F(RMS)}$	4.71	A
サージ順電流 Surge Forward Current	I_{FSM}	80 50Hz 正弦半波, 1サイクル, 非くり返し 50Hz Half Sine Wave, 1cycle, Non-repetitive	A
動作接合温度範囲 Operating Junction Temperature Range	T_{jw}	-40~+150	$^{\circ}C$
保存温度範囲 Storage Temperature Range	T_{stg}	-40~+150	$^{\circ}C$

■OUTLINE DRAWING(mm)



■Approx Net Weight:0.16g

■電氣的・熱的特性 Electrical/Thermal Characteristics

Item	Symbol	Conditions	Min.	Typ.	Max.	Unit
ピーク逆電流 Peak Reverse Current	I_{RM}	$T_j=25^{\circ}C, V_{RM}=V_{RRM}$	—	—	50	μA
ピーク順電圧 Peak Forward Voltage	V_{FM}	$T_j=25^{\circ}C, I_{FM}=3A$	—	—	1.0	V
熱抵抗 Thermal Resistance	$R_{th(j-a)}$	接合部・周囲間*1 Junction to Ambient	—	—	89	$^{\circ}C/W$
		接合部・リード間 Junction to Lead	—	—	13	$^{\circ}C/W$

*1: アルミナ基板実装 /Alumina Substrate mounted (Soldering Lands= 2×3.5 mm, Both Sides)
*2: T_l : リード温度/ T_l : Lead Temperature

■定格・特性曲線

FIG.1

順電圧特性
FORWARD CURRENT VS. VOLTAGE

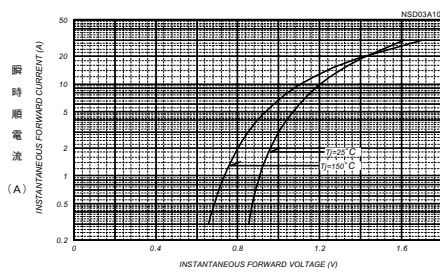


FIG.2

平均順電力損失特性
AVERAGE FORWARD POWER DISSIPATION

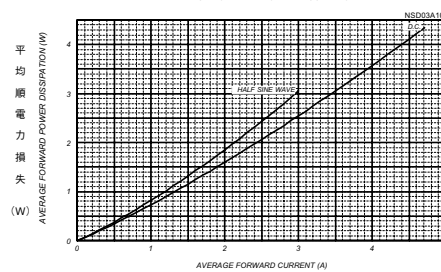


FIG.3

平均順電流一周囲温度定格
AVERAGE FORWARD CURRENT VS. AMBIENT TEMPERATURE
Alumina Substrate Mounted(Soldering Land=2×3.5mm)

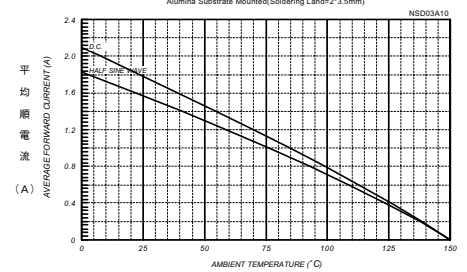


FIG.4

平均順電流一周囲温度定格
AVERAGE FORWARD CURRENT VS. AMBIENT TEMPERATURE
Glass Epoxy Substrate Mounted(Soldering Land=2×3.5mm)

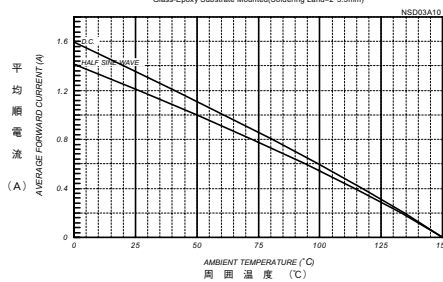


FIG.5

平均順電流-リード温度定格
AVERAGE FORWARD CURRENT VS. LEAD TEMPERATURE

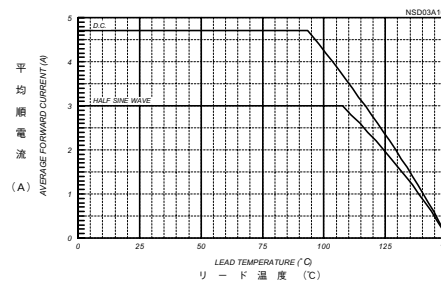


FIG.3

サージ順電流定格
SURGE CURRENT RATINGS
f=50Hz,Half Sine Wave,Non-Repetitive, No Load

